# LASER MACHINING APPARATUS


## Abstract of the Disclosure

Provided is a laser machining apparatus. The laser machining apparatus includes: a laser oscillator emitting laser beams; a first dividing means on which the laser beams emitted from the laser oscillator are incident to be selectively divided so that the incident laser beams progress along at least one path from among a pair of first paths; a second dividing means on which the laser beams that passed through any one of the first paths are incident to be selectively divided so that the incident laser beams progress along at least one path from among a pair of second paths; a third dividing means on which the laser beams that passed through the other one of the first paths are incident to be selectively divided so that the incident laser beams progress along at least one path from among a pair of third paths; four pairs of scanners on which the laser beams that passed through the first, second, and third dividing means are incident to each be deflected onto desired positions on a substrate so as to be processed; and a scan lens on which the laser beams that passed through the four pairs of scanners are incident to be collected on a spot having a predetermined diameter and irradiated onto the substrate.


Figure 2